

Filename: PMP7141 REV\_C\_bom.xls

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## PMP7141 REV\_C BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	47nF	Capacitor, X2 EMI Suppression, 310V, 10%	0.670 X 0.295 inch	BFC233920473	Vishay
1	C4	220uF	Capacitor, Aluminum, 50V, 105C, 20%	0.315 inch	50VZL220uFMxxxxx10x16mm	Rubycon
1	C5	2.2uF	Capacitor, Ceramic, X7R, 50V, 10%	1210	C3225X7R1H225K	TDK
1	C7	15pF	Capacitor, Ceramic, 50V, COG	0603	STD	STD
1	C8	10uF	Capacitor, Ceramic, 50V, X7R, 10%	1210	GRM32ER71H106KA12L	Murata
1	C9	2.2uF	Capacitor, Ceramic, X7R, 25V, 10%	1206	Std	TDK
2	C2-3	0.1uF	Capacitor, Ceramic, 630V, X7R, 10%	1812	Std	Std
1	D2	US1J	Diode, Super Fast Rectifier, 600V, 1A	0.220 x 0.115 inch	US1J	Diodes
1	D3	RH06-T	Bridge Rectifier, 600V, 0.5A, Glass Passivated, Fast Recovery	MiniDIP	RH06-T	Diodes
1	D5	BAV21WS	Diode, Small Signal, 200mA, 250V	SOD-323	BAV21WS	Diodes
1	D6	DNP	DNP	SOD-323	DNP	Std
1	D100	1N4148WS	Diode, Small Signal, 300-mA, 100V	SOD-323	1N4148WS	Fairchild
1	F1	0.5A	Fuse, Radial, Slow Acting, 0.5A, 250V	0.160 x 0.400 inch	0677.500MXE	Littelfuse
4	J1-4	905-0-00-00-00-11-0	Header, SMT Spring Load Pin	0.072 x 0.680 inch	905-0-00-00-00-11-0	Mil-Max
1	L1	4.7mH	Inductor, Power, 4.7mH, 25-Ohm	0.236 inch Dia.	744741472	Wuerth
1	R1	1K	Resistor, Chip 1/4 watt, ± 5%	1206	STD	STD
1	R2	S07K300	Varistor, Disk, 300V, 1W, TA @ 85C°	D Size	SIOV-S07K300	Epcos
1	R4	22	Resistor, Metal Film, 1W, ±5%	{Size}	FMP100JR-52-22R	Yageo
1	R5	221	Resistor, Chip, 1/10W, 1%	0805	STD	STD
1	R7	66.5k	Resistor, Chip, 1/10W, 1%	0603	STD	STD
1	R8	15.0k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R9	5.62k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R10	0	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R11	DNP	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R12	1.2	Resistor, Chip, 1/10W, 1%	0805	STD	STD
2	R3 R6	200k	Resistor, Chip 1/4 watt, ± 5%	1206	STD	STD
1	T1	880uH	Transformer, Flyback	E13/7/4	TBD	Wuerth
1	U1	TPS92311DGS	IC, Off-Line Primary Side Sensing Converter with PFC	SO	TPS92311DGS	Texas Instruments

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
  2. These assemblies must be clean and free from flux and all contaminants.  
Use of no clean flux is not acceptable.
  3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
  4. Ref designators marked with an asterisk (\*\*\*) cannot be substituted.  
All other components can be substituted with equivalent MFG's components.

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